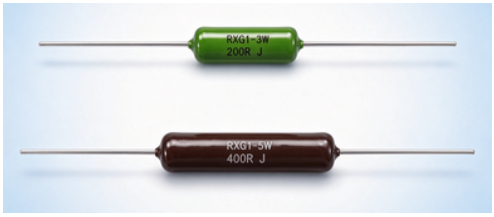
RXG1

Axial Vitreous Enamelled Wirewound Resistors

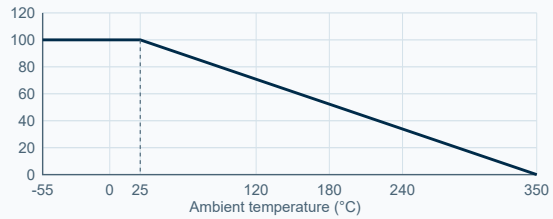


PCB mounting for DC or low-frequency circuits.

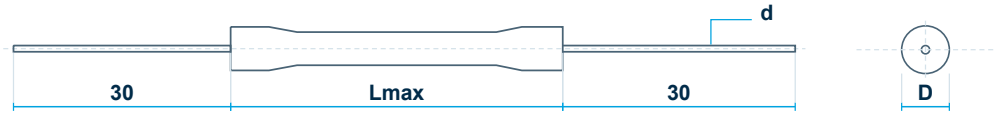
Compact, high power loading · Standard SJ2746-87

Photos illustrate appearance. Use the selection table for ratings.

Ambient temperature derating



Selection data and outline dimensions (mm)



Model	70 °C (W)	25 °C (W)	Range (Ω)	Max. working (V)	Lmax	D	d
RXG1-05	0.5	1	0.1-510	75	10	3.5 ±1	0.8
RXG1-1	1	2	0.1-1 k	100	12	4.5 ±1	0.8
RXG1-3	2.6	3	0.1-2 k	120	12.7	5.6 ±1	0.8
RXG1-5	4.5	5	0.1-4 k	300	22	7 ±1	0.8
RXG1-7	6	7	0.1-6 k	350	24	7.4 ±1	0.8
RXG1-8	7	8	0.5-8 k	500	33	8 ±1	0.8
RXG1-11	9.5	11	0.5-10 k	650	38.1	8 ±1	1
RXG1-15	15	18	0.5-12 k	700	45.8	9.5 ±1	1
RXG1-20	20	23	1-15 k	800	54	9 ±1	1
RXG1-26	25.8	30	0.5-15 k	1000	64	12 ±1	1

Tolerance ±5% (J) · TCR ≤250 ppm/°C · Surface temperature ≤450 °C

Performance tests

Test method reference SJ1330-78

Test	Requirement	Test method
Solderability	Solder flows freely	235 ±5 °C, 2 s, solder bath
Terminal strength	|ΔR| ≤ 1%R + 0.05 Ω	10 N at ≤4.3 W, 20 N at ≥6 W
Overload	|ΔR| ≤ 1%R + 0.05 Ω	Pending confirmation. See note below.
Temperature change	|ΔR| ≤ 1%R + 0.05 Ω	Pending confirmation. See note below.
Bump	|ΔR| ≤ 1%R + 0.05 Ω	390 m/s², 4000 bumps
Shock	|ΔR| ≤ 1%R + 0.05 Ω	490 m/s², 11 ms, 18 shocks
Vibration	|ΔR| ≤ 1%R + 0.05 Ω	10-500 Hz, 98 m/s², 6 h
Temperature rise	≤245 °C	Apply rated power
Steady damp heat	|ΔR| ≤ 5%R + 0.05 Ω	40 ±2 °C, 93 (+2/-0)% RH, 56 h
Room-temperature endurance	|ΔR| ≤ 5%R + 0.05 Ω	Room temperature, rated power, 1000 h

The source lists -55 / +200 °C, 5 cycles for overload and a 235 ±5 °C, 2 s solder bath for temperature change.
Both test methods require confirmation.

Hunan INLANX Electronic Technology Co., Ltd.
contact@inlanx.com